New SEMI Europe Summit to Highlight 3D, MEMS and Image Sensors Technology Trends Driving Innovation – July 16, 2021

BERLIN, Germany - July 6, 2021 - 3D semiconductor technologies and MEMS and image sensors will take center stage 1-3 September, 2021, at the SEMI Connecting Heterogeneous Systems Summit (CHSS) as industry experts from across the value chain gather to highlight the latest heterogeneous integration and sensing technology advances that are driving innovation in high-end applications. The virtual event co-locates the SEMI 3D & Systems and MEMS & Imaging Sensors Summits. Registration is open.

"Advances in heterogenous integration and sensors are crucial to driving digital transformation," said Laith Altimime, president of SEMI Europe. "The SEMI Connecting Heterogenous Systems Summit will gather semiconductor industry leaders to discuss the next wave of innovations and key digital technologies that will redefine how we work and live in the digital age."

The Connecting Heterogeneous Systems Summit will kick off with keynotes from technology leaders.

Keynote Speakers

- Kaladhar Radhakrishnan, Fellow , Intel
- Barbara De Salvo, Silicon Technology Strategist, Facebook
- Haechang Lee, Senior VP, Automotive Sensors, Samsung Electronics
- Dr. Walter Weigel, VP, Huawei European Research Institute
- Frank van de Scheur, GM, Business MEMS & Micro Devices, Philips

Day One

A joint session on the emerging technology roadmaps for 3D, MEMS and imaging applications will offer insights into innovation and market growth opportunities for advanced semiconductors, including packaging technologies for high-performance computing and new applications for MEMS and image sensors. Day one will also feature two parallel tracks:

- Equipment and materials for enabling high performance
- Equipment and materials for new MEMS and image sensors

Attendees are invited to participate in the round-table discussions and the networking mixer to discuss day-one topics.

Day Two

The joint session on diversity and inclusion will explore strategies for empowering the next generation of semiconductor professionals in an inclusive work environment. Two parallel tracks will feature presentations covering topics including system-level requirements for 3D and systems, advanced MEMS and imaging systems technology roadmaps, and design and architecture.

Participants are welcome to join any workshop and participate in discussions during the Technology Deep Dives session showcasing technology trends, case studies and best practices.

Day Three

The Technology Showcase will feature leading-edge products recently launched in the fields of 3D, heterogeneous integration, MEMS and imaging. Winners will be announced during the summit and receive a complimentary exhibition booth at CHSS 2022.

Premium corporate sponsors are Atotech , Evatec , EV Group (EVG) , Infineon , JSR Micro , SPTS, a KLA Company , BESI , ULVAC , Lam Research , Okmetic , SCHOTT and SUSS MicroTec . Event sponsors are, AEM Afore Oy , Edwards , Invest in Grenoble Alps , Merck , and Polyteknik .

For more information, see the Connecting Heterogeneous Systems Summit program. Please contact Adi Hodorov at ahodorov@semi.org about sponsorship opportunities.

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